

Claims

1 An optical transceiver module (1) comprising a housing (2) having disposed therein a transmitter and a receiver, characterized in that said housing further comprises a pair of rails (6) disposed on opposite sides of said housing, said rails having a plurality of spring-like fingers (260) arranged to enable said module to be removably inserted into a suitably configured board (35).

2 A module as claimed in Claim 1, wherein electrical connection means (7) are disposed at a back end of said module.

3 A module as claimed in Claims 1-2, wherein said housing includes a plurality of fins (9) disposed thereon and arranged to facilitate temperature control of said module.

4 A module as claimed in Claims 1-3, wherein said module includes a bezel (3) disposed at a front end of said module, said bezel having a pair of arms (20, 22) each extending from diagonally opposite corners of said bezel.

5 A module as claimed in any preceding Claim, wherein said housing comprises an upper half (110) and a lower half (112) sandwiched together, and an electrically conductive gasket (115) disposed there between to facilitate electrical connection between said upper and lower halves.

6 An optical transceiver system comprising a module as claimed in any preceding Claim, wherein said system further comprises a chassis (30) having said suitably configured board (35) disposed therein, and chassis electrical

connector means (37) arranged to receive said module electrical connector means (7).

7 A system as claimed in Claim 6, wherein said suitably configured board (35) is disposed within said chassis on a plurality of mounting means (250) so as to enable air to pass both above and below said module.

8 A system as claimed in Claims 6-7, wherein said system further comprises shield means (36) disposed substantially around said module and said system electrical connectors so as to provide electrical connection from said module to said suitably configured board.

9 A system as claimed in Claim 8, wherein said shield means includes a plurality of resilient fingers (420) arranged to exert pressure on said housing so as to improve electrical connection between said housing and said shield means.

10 A system as claimed in any of preceding Claims 6-9, wherein a layer of electrically conductive material (400) is disposed on said suitably configured board (35) in an area substantially surrounding said module, so as to further improve electrical connection between said module and said chassis.

11 A system as claimed in Claim 10, wherein said layer of electrically conductive material in gold.

12 A system as claimed in any of preceding Claims 7-11, wherein said module (1) , said chassis (30) and said suitably configured board (35) are electrically grounded.

13 An optical telecommunications network comprising a system or module as claimed in any preceding Claims.